

Foxconn Interconnect Technology (FIT) Advances Next-Generation 448G Twin-ax Cable Development, Powered by Testing on the World's Premier Broadband VNA — Anritsu VectorStar™ ME7838AX 125 GHz

Morgan Hill, CA– February 24, 2026 – Anritsu Company and FIT are jointly demonstrating FIT's next-generation high-speed cable capable of 448G per lane, delivering up to 3.2T total throughput (448G × 8 lanes). Designed to meet the extreme bandwidth demands of generative and re-generative AI systems, the new cables leverage advanced technology to achieve these unprecedented data rates.

To validate cable performance at these speeds, FIT utilized the Anritsu VectorStar ME7838AX Broadband VNA, providing accurate characterization from 70 kHz to 125 GHz. Measurements confirm excellent insertion loss, return loss, and overall signal integrity reflecting both FIT's cable innovation and Anritsu's precision test capabilities.

As data rates continue to rise, test bandwidth requirements will exceed 125 GHz. Anritsu's VectorStar platform offers a smooth, cost-effective upgrade path to 145 GHz and 220 GHz, ensuring customers can scale as new interconnect standards emerge. Engineers can also use VectorStar's time-domain capabilities to visualize advanced eye diagrams, enabling early insight into real-world signal performance during RF test.

With the industry transition underway from 224G per lane PAM4 to 448G per lane PAM6, the need to address copper-based signal integrity challenges including attenuation, reflections, crosstalk, thermal management, and connector performance has intensified.

FIT's 448G solution delivers:

- Extremely low insertion loss
- Wide-open advanced eye diagrams
- High-performance connector enablement for ultra-high speeds

Together, Anritsu and FIT are enabling the next generation of high-speed data center and AI infrastructure.

Visit DesignCon and stop by FIT at booth #719 and Anritsu at booth #1143 to experience live demonstrations of our latest technologies.

About Foxconn Interconnect Technology (FIT Hon Teng)

Foxconn Interconnect Technology (FIT HKEX: 6088) is a leading global solutions developer and manufacturer, cultivating connectivity for a better world. With unsurpassed capabilities in development, research, manufacturing engineering and design, production, supply chain, and go-to-market planning for world class brands and private label products spanning B2C and B2B categories, FIT is at the forefront of worldwide technological trends delivering compelling user experiences at scale. With offices and manufacturing sites located in Asia, the Americas and Europe, FIT is a global leader in the manufacturing of high precision interconnect components.

For more information visit <https://www.fit-foxconn.com>

About Anritsu

Anritsu is a provider of innovative communications test and measurement solutions. Anritsu engages customers as true partners to help develop wireless, optical, microwave/RF, and digital solutions for R&D, manufacturing, installation, and maintenance applications, as well as multidimensional service assurance solutions for network monitoring and optimization. Anritsu also provides precision microwave/RF components, optical devices, and high-speed electrical devices for communication products and systems. The company develops advanced solutions for emerging and legacy wireline and wireless technologies used in commercial, private, military/aerospace, government, and other markets.

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